

Features

- Very low FOM $R_{DS(on)} \times Q_G$
- 100% avalanche tested

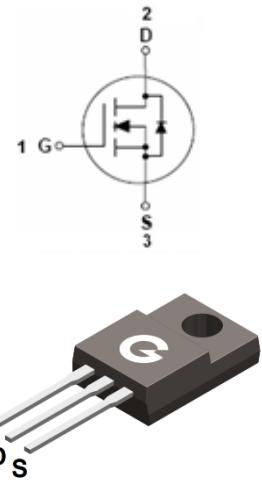
HF

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Mechanical Data

- Case: ITO-220AB
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



ITO-220AB

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
SJ70R550F	ITO-220AB	50 pcs / Tube	SJ70R550F

Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	700	V
Gate-to-Source Voltage	V_{GSS}	± 30	V
Continuous Drain Current ($T_C = 25^\circ\text{C}$)	I_D	11	A
Continuous Drain Current ($T_C = 100^\circ\text{C}$)	I_D	6.8	A
Pulsed Drain Current * ¹	I_{DM}	33	A
Single Pulse Avalanche Energy * ²	E_{AS}	211	mJ

Thermal Characteristics

Parameter	Symbol	Value	Unit
Power Dissipation($T_C = 25^\circ\text{C}$)	P_D	31.3	W
Thermal Resistance Junction-to-Air	$R_{\theta JA}$	80	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	4	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	T_J	-55 ~ +150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 ~ +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}$, $I_D = 250\mu\text{A}$	700	-	-	V
$I_{DS(0)}$	Zero Gate Voltage Drain Current	$V_{DS} = 700\text{V}$, $V_{GS} = 0\text{V}$	-	-	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS} = \pm 30\text{V}$, $V_{DS} = 0\text{V}$	-	-	± 100	nA
On Characteristics						
$R_{DS(ON)}$	Static Drain-Source On-resistance ^{*3}	$V_{GS} = 10\text{V}$, $I_D = 5.5\text{A}$	-	-	0.55	Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$	2.5	-	4.5	V
g_f	Forward Transconductance ^{*3}	$V_{DS} = 10\text{V}$, $I_D = 5.5\text{A}$	-	7.8	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}$	-	909	-	pF
C_{oss}	Output Capacitance	$V_{DS} = 50\text{V}$	-	45	-	
C_{rss}	Reverse Transfer Capacitance	$f = 1.0\text{MHz}$	-	3.4	-	
Switching Characteristics						
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD} = 400\text{V}$ $R_G = 25\Omega$ $I_D = 11\text{A}$	-	41	-	ns
t_r	Turn-on Rise Time		-	20	-	
$t_{d(OFF)}$	Turn-Off Delay Time		-	123	-	
t_f	Turn-Off Fall Time		-	6.4	-	
Q_G	Total Gate-Charge	$V_{DD} = 560\text{V}$ $V_{GS} = 10\text{V}$ $I_D = 11\text{A}$	-	21	-	nC
Q_{GS}	Gate to Source Charge		-	4.7	-	
Q_{GD}	Gate to Drain (Miller) Charge		-	7.3	-	
Source-Drain Diode Characteristics						
V_{SD}	Diode Forward Voltage	$I_{SD} = 11\text{A}$, $V_{GS} = 0\text{V}$, $T_J = 25^\circ\text{C}$	-	-	1.2	V
I_S	Diode Continuous Forward Current	$T_c = 25^\circ\text{C}$	-	-	9.2	A
I_{SM}	Pulsed Source-Drain Current		-	-	29	A
t_{rr}	Reverse Recovery Time	$I_S = I_F = 9.2\text{A}$, $V_R = 560\text{V}$ $di/dt = 100 \text{ A}/\mu\text{s}$	-	280	-	ns
Q_{rr}	Reverse Recovery Charge		-	2.8	-	μC

Notes:

- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{AS} = 1.6\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
- Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty Cycle $\leq 1\%$

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

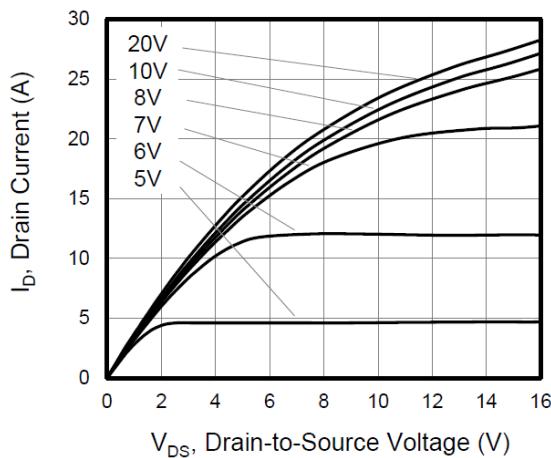


Fig 1 Typical Output Characteristics

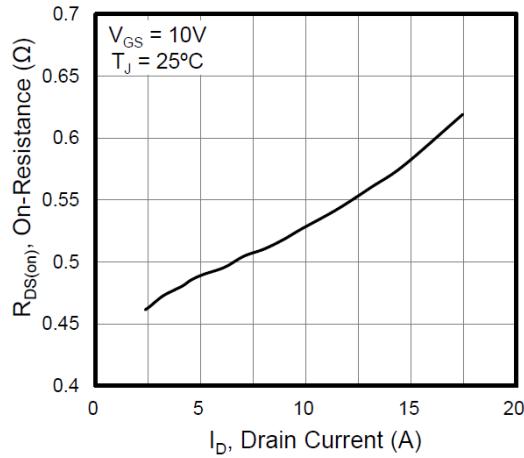


Fig 2 On-Resistance vs. Drain Current and Gate Voltage

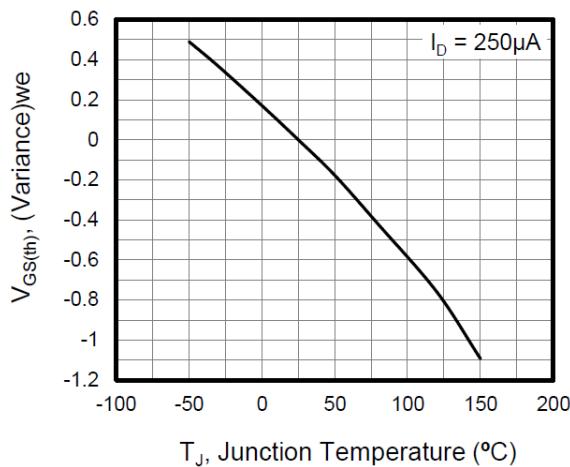


Fig 3 Normalized $V_{GS(th)}$ vs. Junction Temperature

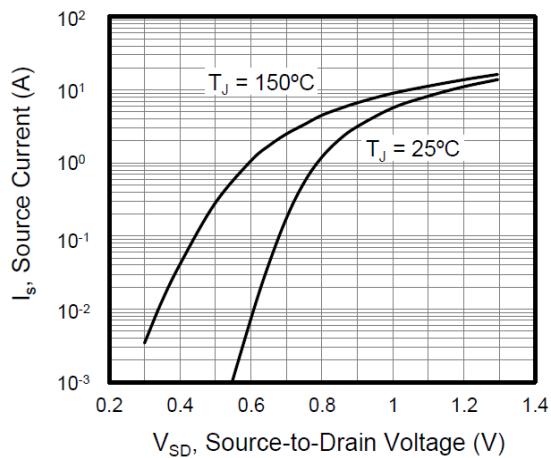


Fig 4 Body-Diode Characteristics

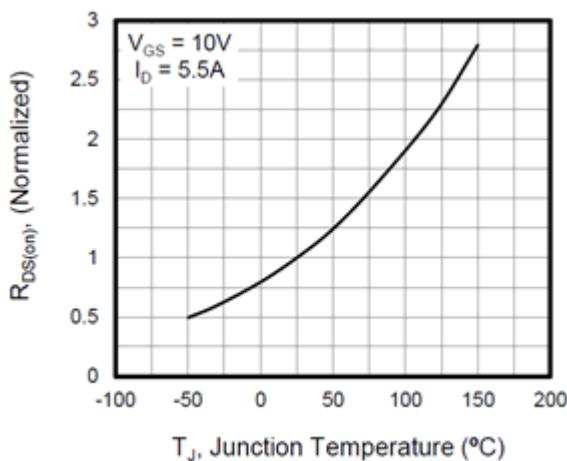


Fig 5 Normalized On-Resistance vs. Junction Temperature

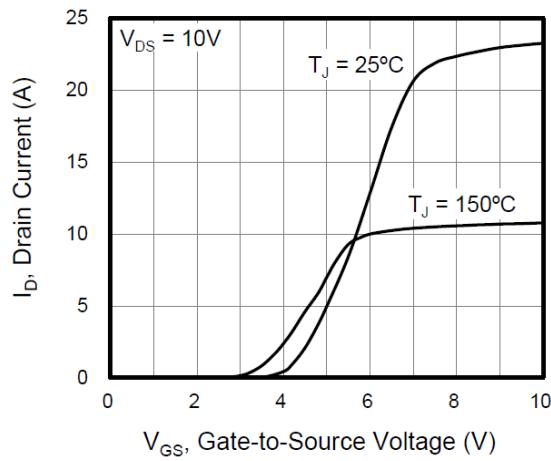


Fig 6 Transfer Characteristics

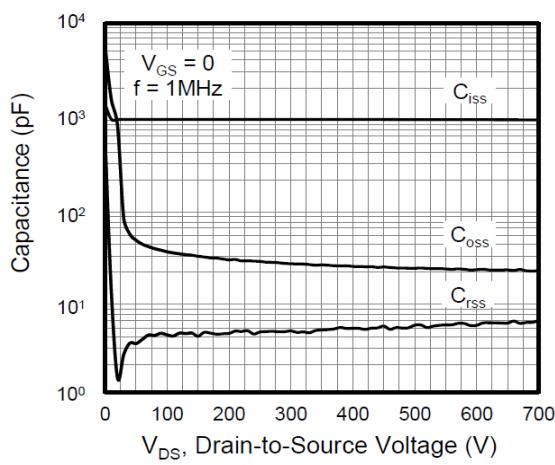


Fig 7 Capacitance Characteristics

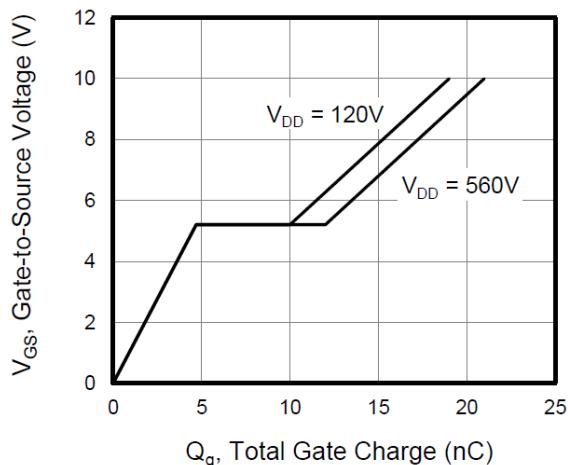


Fig 8 Gate-Charge Characteristics

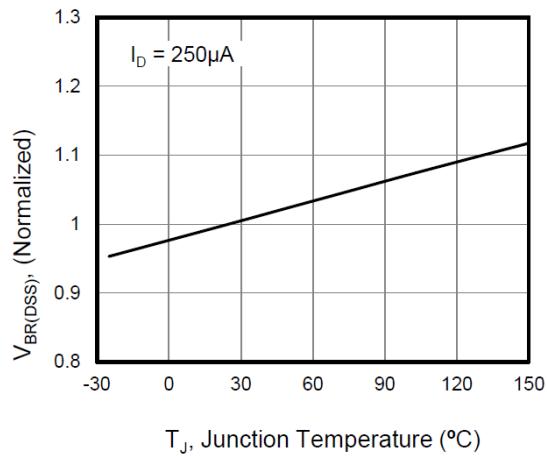


Fig 9 Normalized Breakdown Voltage
vs. Junction Temperature

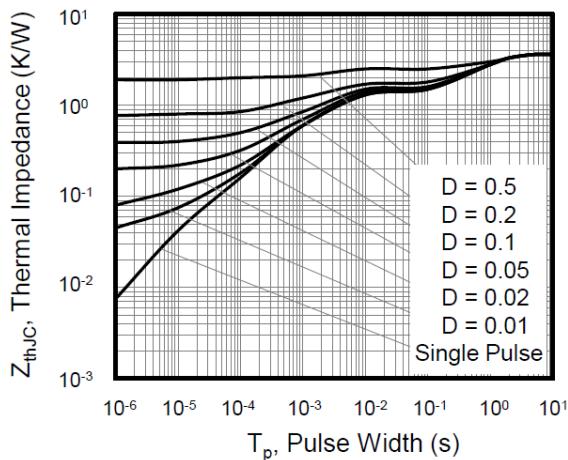


Fig 10 Maximum transient thermal
impedance

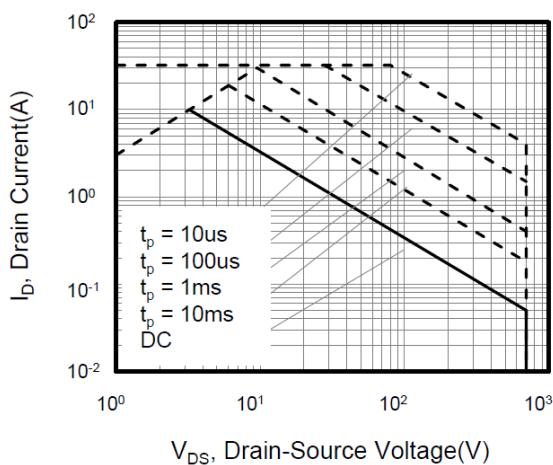
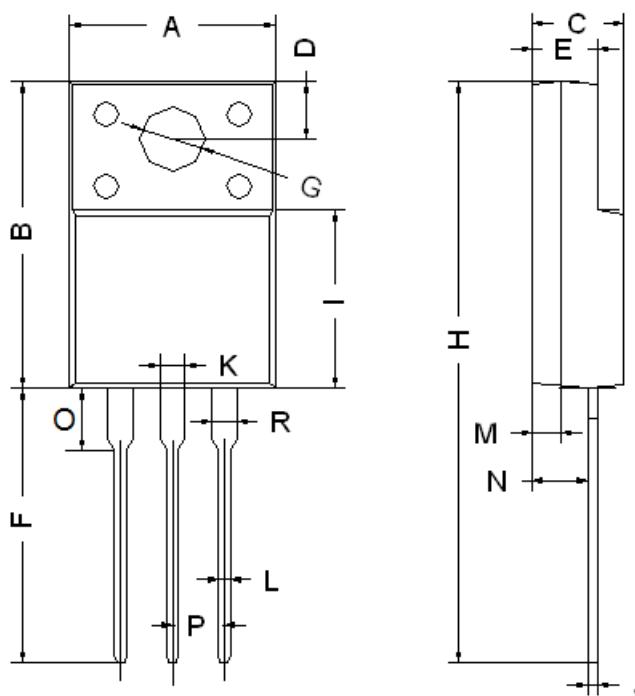


Fig 11 Safe Operation Area

Package Outline Dimensions (Unit: mm)



ITO-220AB		
Dimension	Min.	Max.
A	9.90	10.30
B	14.80	15.20
C	4.30	4.70
D	2.50	2.90
E	2.80	3.30
F	13.00	13.60
G	3.10	3.30
H	28.00	28.60
I	7.90	8.90
J	0.40	0.60
L	0.70	0.90
M	1.30	1.50
N	2.60	2.80
O	2.60	3.10
P	2.45	2.65
K/R	1.10	1.30

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